

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SEUNGWON IM	10/11/2017
MANKYO JONG	10/25/2017
JOONSEO SON	10/25/2017
OSEOB JEON	10/11/2017
RECEIVING PARTY DATA	
Name:	FAIRCHILD KOREA SEMICONDUCTOR LTD.
Street Address:	55, PYEONGCHEON-RO 850 BEON-GIL, WONMI-GU, GYEONGGI-DO
City:	BUCHEON
State/Country:	KOREA, REPUBLIC OF
Postal Code:	14487
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15729973
CORRESPONDENCE DATA	
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NAME OF SUBMITTER:	SHARRON CASTILLO
SIGNATURE:	/Sharron Castillo/
DATE SIGNED:	10/25/2017
Total Attachments: 3	
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source=FSC75398US_20171025_Assignment#page2.tif	

ASSIGNMENT & AGREEMENT

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we,

Name	of (City and State OR Country)
SEUNGWON IM	BUCHEON-SI KOREA, REPUBLIC OF (KR)
MANKYO JONG	BUCHEON-SI KOREA, REPUBLIC OF (KR)
JDONSEO SON	SEOUL KOREA, REPUBLIC OF (KR)
OSEOB JEON	SEOUL KOREA, REPUBLIC OF (KR)

agree to sell, assign, and transfer, and do hereby sell, assign, and transfer to Fairchild Korea Semiconductor Ltd., a limited liability company of Korea, Republic of, having its principal office in Bucheon Korea, Republic of, and its successors, assigns, and legal representatives ("FKS"), the entire right, title, and interest in and to the inventions and discoveries as described, illustrated, and/or claimed in

Title: SEMICONDUCTOR DIE PACKAGE AND MANUFACTURING METHOD

Attorney Docket No.: FSC75398US

Serial No.: 15/729973

Filing Date: October 11, 2017

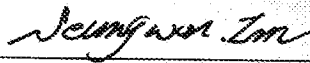
together with the entire right, title, and interest in and to the above listed application(s), and in and to any and all provisional, non-provisional, divisional, continuation, continuation-in-part, international, foreign, and any and all other applications related thereto, and also including any and all grants, issuances, letters patent, reissues, reexaminations, renewals, priority rights, and priority claims related to any of the foregoing, and any and all rights to collect past damages for infringement of any of the foregoing (the "Patent Rights").

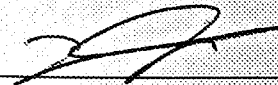
We further authorize FKS to apply for and hold and maintain the Patent Rights throughout the world directly in its own name or any other name which FKS deems appropriate in its sole discretion, and to claim the priority of the filing date of the above listed application(s).

We agree that, when requested, we will, without charge to FKS, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing, maintaining, and enforcing the Patent Rights in any and all countries and for vesting title thereto in FKS or its nominees.

We represent and warrant that we have full right to convey the entire right, title and interest herein sold, assigned, and transferred, and that the Patent Rights hereby conveyed are free from all prior assignment, grant, mortgage, license, or other encumbrance to anyone other than FKS. We covenant and further warrant that we will not convey hereafter any part of the Patent Rights to anyone other than FKS or do any act whatsoever conflicting with this ASSIGNMENT & AGREEMENT.

We hereby authorize FKS or anyone it may properly designate to insert in this ASSIGNMENT & AGREEMENT the filing date and serial number of the above listed application(s) when ascertained. More than one counterpart of this ASSIGNMENT & AGREEMENT may be executed, each of which will be deemed an original.

By (Inventor signature): 
Seungwon Im

Witnessed by (Witness signature): 

Printed name of Witness: Yoon Soo Lee

Signed and Witnessed on (date): 11 Oct 2017

By (Inventor signature): _____
Mankyo Jong

Witnessed by (Witness signature): _____

Printed name of Witness: _____

Signed and Witnessed on (date): _____


By (Inventor signature): _____
Joonsoe Son

Witnessed by (Witness signature): _____

Printed name of Witness: _____

Signed and Witnessed on (date): _____

By (Inventor signature): 
Oseob Jeon

Witnessed by (Witness signature): 

Printed name of Witness: Yoon Soo Lee

Signed and Witnessed on (date): 11 Oct 2017

By (Inventor signature): _____
Seungwon Im

Witnessed by (Witness signature): _____

Printed name of Witness: _____

Signed and Witnessed on (date): _____

By (Inventor signature): *Jong*
Manryo Jong

Witnessed by (Witness signature): *[Signature]*

Printed name of Witness: SangEui Han

Signed and Witnessed on (date): 2017/10/25

By (Inventor signature): *Joonsoo Son*
Joonsoo Son

Witnessed by (Witness signature): *[Signature]*

Printed name of Witness: SangEui Han

Signed and Witnessed on (date): 2017/10/25

By (inventor signature): _____
Oseob Jeon

Witnessed by (Witness signature): _____

Printed name of Witness: _____

Signed and Witnessed on (date): _____